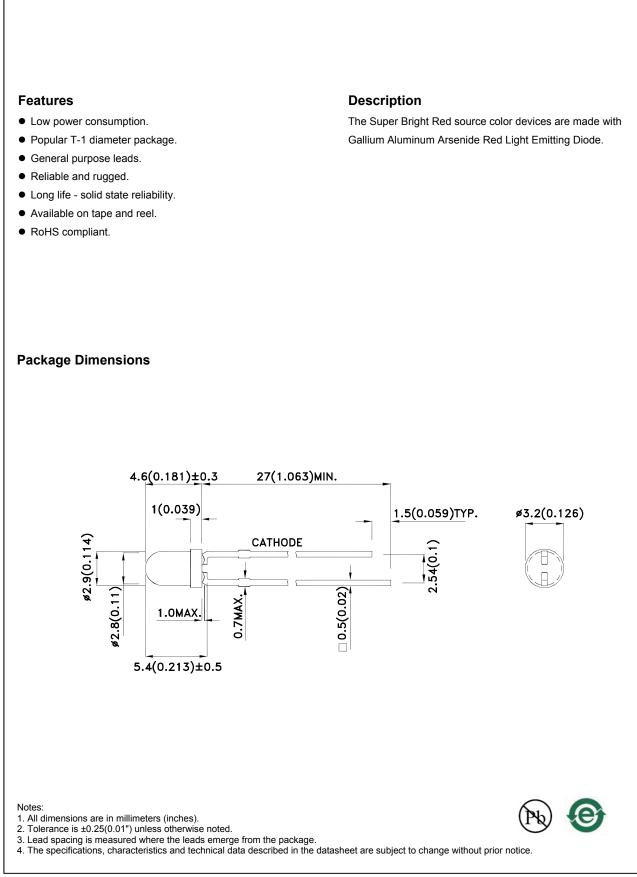
T-1 (3mm) SOLID STATE LAMP

Part Number: WP710A10SRC/E Super Bright Red



SPEC NO: DSAL0548 APPROVED: WYNEC REV NO: V.2 CHECKED: Allen Liu DATE: MAR/07/2011 DRAWN: J.Yu



Selection Guide

Selection Guide					
Part No.	Dice	Lens Type		cd) [2] 0mA	Viewing Angle [1]
			Min.	Тур.	201/2
WP710A10SRC/E	Super Bright Red (GaAlAs)	Water Clear	700	900	34°

Notes:

01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	660		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	I⊧=20mA
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	IF=20mA
lr	Reverse Current	Super Bright Red		10	uA	VR = 5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

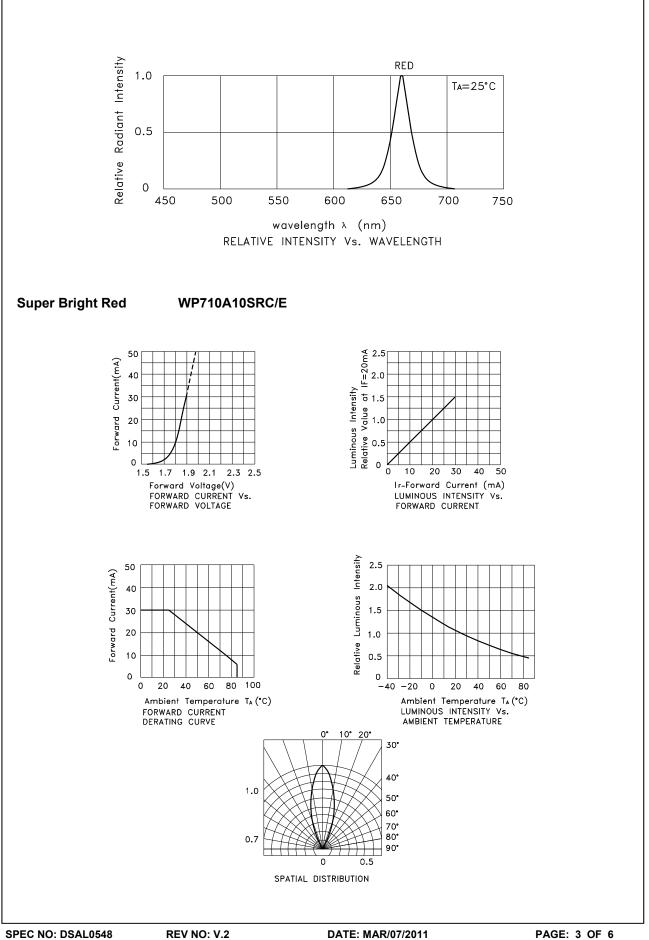
Absolute Maximum Ratings at TA=25°C

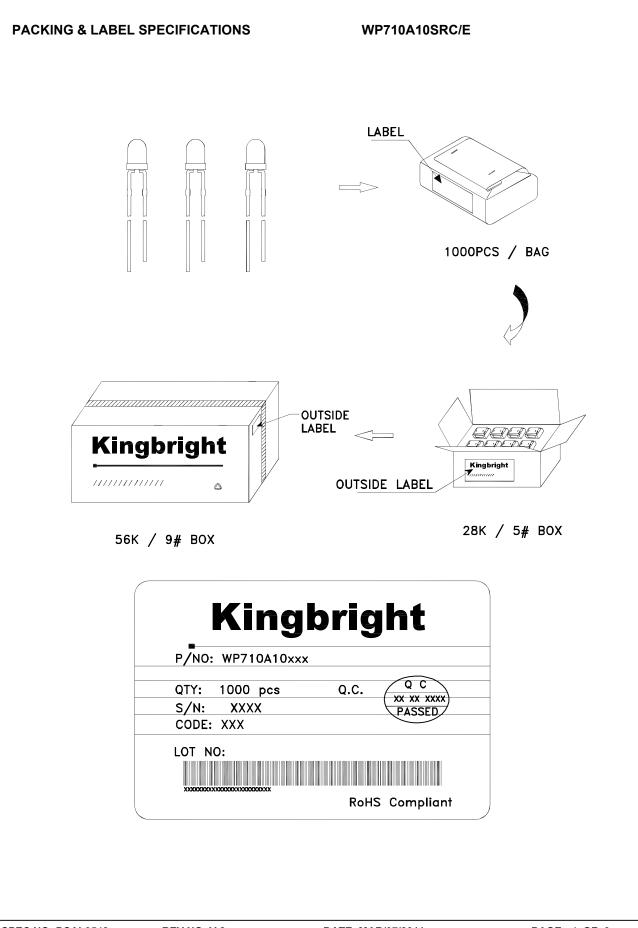
Parameter	Super Bright Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	155	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

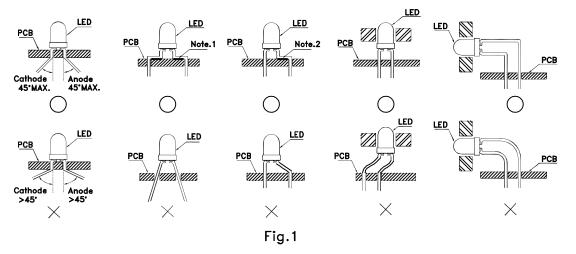
2. 2mm below package base.
3. 5mm below package base.



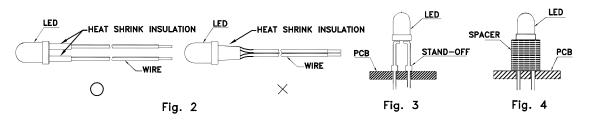


PRECAUTIONS

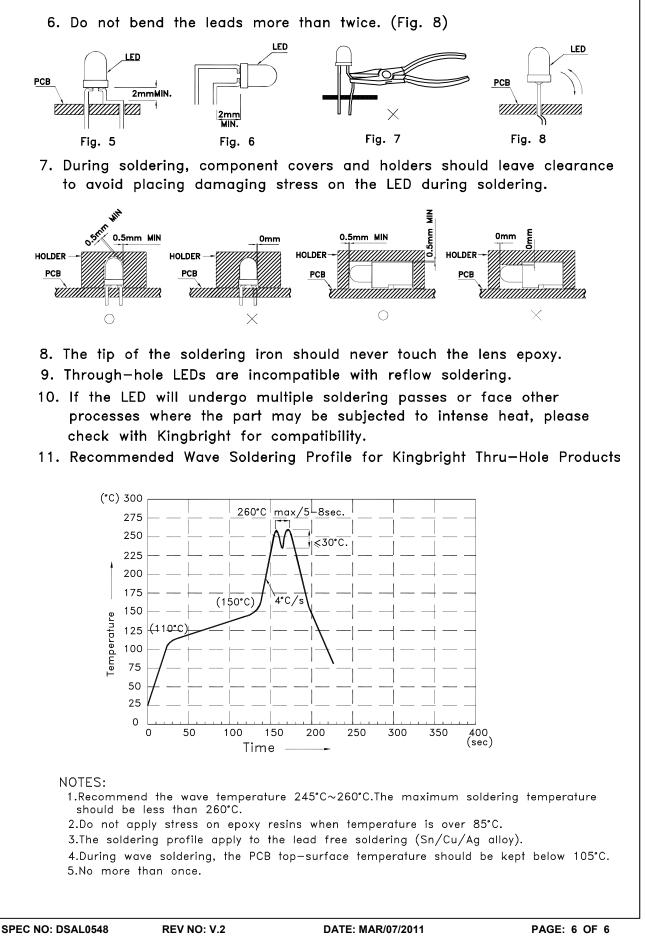
1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



- \supset " Correct mounting method "imes " Incorrect mounting method
- 2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig.2)
- 3.Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



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